



**CYPRESS SEMICONDUCTOR CORPORATION**

**DATE:** December 6, 2005  
**TO:** Attendees (brt,csd,bck,yqj,kxf), ltx, wrs, smt, mxp  
**AUTHOR:** Ken Freed

**PURPOSE:** Salient Points from this Afternoon's Die Retest Meeting

21Oct05 Schedule (from memo kxf-144):

October 05		November 05				December 05				January 06		
24	31	7	14	21	28	5	12	19	26	2	9	16
				24,25 Holiday					26-30,2 Holiday			
Develop Code to Shift Test Head for Retest 24 days timespan complete 12/01/05						Run Qual Wafers & Debug 15 day timespan 12/01-12/22 completed 12/23				Specs/PCR 8 day timespan completed 1/12		

we are here

**Problems:**

1. We aren't running wafers through the new software fast enough to make the schedule.
  - Despite excellent support, rsc'ing lots, waiting for them to hit production, and getting/switching the tool is taking too long.
    - In two weeks we've run 18 wafers from 4 lots.
2. We cannot get enough (any) production wafers for some probe card configurations.

**Solutions:**

1. We will leave the new software on VT-27 for running 200 to 500 device 6370 production wafers. There wafers will NOT be reprobred.
  - Brt/Ltx will "wordsmith" a bunch of rsc's to keep wafers going through VT-27
  - For yield and correlation purposes, these lots will be split. Half the lot will be run on VT-27 (under the new software) and half on another tester.
  - Kxf will train some operators on all shifts to use the new software.
  - Kxf will record all software tweaks (what, when).

- The goal is to run 200 wafers without having to tweak the software.
- Kxf will continue to collect runtime, yield, and bin change data on these wafers.
- Kxf will track the retest splits and solicit feedback information on them from CML

2. In parallel to the above effort, we will test/debug the remaining probe card configurations on another tester, with scrap wafers if necessary:

1	Neg Sloped Dual 7C53120CT	eng/dt153120.kxf RE_TEST 5 1 1000 RE_TEST 9 1 1000 RE_TEST 12 1 1000
2	Pos Sloped Dual 6341	eng/dt16c341.kxf RE_TEST 3 1 1000 RE_TEST 4 1 1000 RE_TEST 5 1 1000
3	Pos Sloped Dual 6602	eng/dt16c602.kxf RE_TEST 3 1 1000 RE_TEST 4 1 1000 RE_TEST 5 1 1000

- When KXF is done testing on this tester, it will be converted back to the existing software (via hard disk swap) and returned to production.

### Remaining Problems/Unknowns

We do know whether we will be able to run enough wafers, for all of our probe card configurations, under the new software, for the 1/12/06 turn on.

- Some of the low quantity devices might not be tested enough.
  - We will have wait and see:
    - how many wafers we can run
    - of which devices / probe card configurations
    - with what software tweaks
- before coming up with a rollout plan.